

**FOR IMMEDIATE RELEASE**

**Pac Tech Announces Grand Opening Celebration for  
the Pac Tech Group of Companies New Asian Facility**

*Grand opening and technical symposium scheduled  
for September 18 and 19 at the new facility in Penang, Malaysia*

**Nauen, Germany—August 19, 2008**—Pac Tech Packaging Technologies, is planning a grand opening celebration on September 18 at its new 55,000 square foot facility in Penang, Malaysia. In conjunction with the opening celebrations, Pac Tech will be holding a technical symposium on September 19 at the Equatorial Hotel in Penang. The opening celebration and symposium will bring the guest up to date on all of the capabilities of the facility, and inform them on new developments in packaging technology. The facility is located at 11900 Bayan Lepas, Bayan Lepas Industrial Zone, Penang, Malaysia. Government officials, dignitaries and industry leaders will be in attendance.

The new facility provides state-of-the-art wafer bumping and backend processing for semiconductor companies within the Pacific Rim. The building has 40,000 square feet of remodeled production floor space, including cleanroom area. Both are equipped with the latest generation equipment for 300mm wafers.

The new Malaysian facility is designed and laid-out to accommodate mass-production, and is capable of handling up to 600,000 wafers per year. Pac Tech Asia will provide a variety of special applications designed to enhance and support the Asian semiconductor manufacturing community. The applications supported will include: electroless Ni/Au under-bump metallization for copper and aluminum devices, solder-paste stencil printing for flip-chips, solder-ball placement for wafer-level CSPs down to 200µm ball diameters, and micro solder-ball placement for fine-pitch applications down to 80µm. More advanced applications include: Ni/Pd/Au metalization for today's power MOSFET devices and gold wire bonding, tall Ni/Au bumping for RFID applications. The facility offers up to 300mm wafer processing capability.

The facility is now accepting process qualification orders. Semiconductor companies can begin to provide Pac Tech GmbH and Pac Tech USA with their wafer forecasts in order to begin allocation of time and schedule them into the production planning. Pac Tech GmbH and Pac Tech USA can also be contacted to begin the pre-qualification of processes to be used in the new Asian facility.

The initially processes flow capability will include: Low-cost wafer-bumping using electroless Ni/Au and Ni/Pd, solder stencil printing, solder-ball placement for wafer-level CSP, wafer thinning, backside metal sputtering, wafer backside laser marking, and wafer sawing. Beginning in 2009, the facility will also offer electrical testing and tape-and-reel processing.

“This grand opening of our new Asian facility provides us an opportunity to showcase the most cost-effective source of wafer bumping and backend processing in the world.”  
Comments Dr. Elke Zakel, President and CEO of Pac Tech GmbH.

Dr. Thorsten Teutsch, President of Pac Tech USA and Vice President of Operations for Pac Tech Asia, comments, “The new facility in Malaysia establishes our global presence. It will also help Pac Tech USA address new customers and increase our domestic business as an entry portal for high-volume customers to our Asian facility.”

### **About Pac Tech**

Pac Tech – Packaging Technologies, founded 1995 with facilities in Nauen, Germany, Santa Clara, California and now in Penang, Malaysia is a world-leader in low-cost wafer bumping processes specializing in electroless nickel under-bump metallization. Pac Tech also designs and manufactures advanced packaging equipment for electroless nickel under-bump metallization and solder-jetting using laser heating. Since its inception, Pac Tech has received more than 50 patents for products developed in areas relating to wafer bumping, flip-chip and chip-scale packaging, and laser-bonding technology. Its website is [www.pactech.com](http://www.pactech.com).

● \* \* END \* \* \*

For additional information, please contact:

*Dr. Elke Zakel*  
*President and CEO*

*Thomas Oppert*  
*Vice President*  
*Worldwide Sales &*  
*Marketing*

*Dr. Thorsten Teutsch*  
*President, Pac Tech USA*  
*Vice President of*  
*Operations, Pac Tech Asia*

*Pac Tech GmbH*  
*Tel: +49-3321-4495-100*  
[zakel@pactech.de](mailto:zakel@pactech.de)

*Pac Tech GmbH*  
*Tel: +49-3321-4495-100*  
[oppert@pactech.de](mailto:oppert@pactech.de)

*Pac Tech USA*  
*Tel: +1-408-588-1925*  
[teutsch@pactech-usa.com](mailto:teutsch@pactech-usa.com)